



Material Content Data Sheet



Sales Product Name		ESD207-B1-02ELS E6327		Issued		20. July 2018		
MA#		MA001613942						
Package		PG-TSSLP-2-3		Weight*		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.17		1668	
	noble metal	gold	7440-57-5	0.001	0.65		6461	
	inorganic material	silicon	7440-21-3	0.011	5.24	6.06	52403	60532
leadframe	non noble metal	nickel	7440-02-0	0.108	51.64	51.64	516574	516574
wire	non noble metal	copper	7440-50-8	0.002	0.74	0.74	7374	7374
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1859	
	plastics	epoxy resin	-	0.011	5.40		53957	
	inorganic material	silicondioxide	60676-86-0	0.066	31.63	37.22	316308	372124
leadfinish	noble metal	gold	7440-57-5	0.004	1.76	1.76	17626	17626
plating	noble metal	palladium	7440-05-3	0.001	0.61		6113	
	noble metal	gold	7440-57-5	0.004	1.97	2.58	19657	25770
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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